

Session Title:	[WB3] Advanced CMP Related Materials
Session Date:	November 16 (Wed.), 2022
Session Time:	15:10-16:10
Session Room:	Room B (Grand Ballroom 1, 2F)
Session Chair:	Prof. Haedo Jeong (Pusan Nat'l Univ., Korea)

[WB3-1] 15:10-15:30

Investigation of Cleaning Effects for Nano-Sized Particles on the Polished Thin Films Using CO₂ Gas Cluster

Kihong Park, Pengzhan Liu, Chengxi Yao, Sanghuck Jeon, and Taesung Kim (Sungkyunkwan Univ., Korea)

[WB3-2] 15:30-15:50

Mechanism of PVA-Brush Loading with Colloidal Silica and Metal Ions during Cu Post-CMP Cleaning Process

Sanjay Bisht, Jerome Peter, Samrina Sahir, Young Jung Kim, Tae-Gon Kim, and Jin-Goo Park (Hanyang Univ., Korea)

[WB3-3] 15:50-16:10

Investigations of Thermal Effect in Copper CMP and PCMP Cleaning

Pengzhan Liu (Sungkyunkwan Univ., Korea), Seokjun Hong (Samsung Electronics Co., Ltd., Korea), and Taesung Kim (Sungkyunkwan Univ., Korea)